

# HiPerFET™ Power MOSFETs

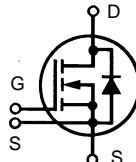
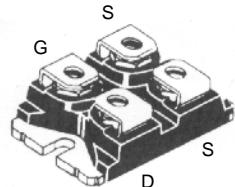
## Single Die MOSFET

**IXFN 26N90**
**IXFN 25N90**

<b>V<sub>DSS</sub></b>	<b>I<sub>D</sub> (cont)</b>	<b>R<sub>DS(on)</sub></b>	<b>t<sub>rr</sub></b>
900 V	26 A	0.30 Ω	250 ns
900 V	25 A	0.33 Ω	250 ns

N-Channel Enhancement Mode  
Avalanche Rated, High dv/dt, Low t<sub>rr</sub>

Preliminary data sheet


**miniBLOC, SOT-227 B (IXFN)**  
 **E153432**

G = Gate      D = Drain  
S = Source

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

<b>Symbol</b>	<b>Test Conditions</b>	<b>Maximum Ratings</b>		
<b>V<sub>DSS</sub></b>	T <sub>J</sub> = 25°C to 150°C	900	V	
<b>V<sub>DGR</sub></b>	T <sub>J</sub> = 25°C to 150°C; R <sub>GS</sub> = 1 MΩ	900	V	
<b>V<sub>GS</sub></b>	Continuous	±20	V	
<b>V<sub>GSM</sub></b>	Transient	±30	V	
<b>I<sub>D25</sub></b>	T <sub>C</sub> = 25°C	26N90	26	A
		25N90	25	
<b>I<sub>DM</sub></b>	T <sub>C</sub> = 25°C, pulse width limited by T <sub>JM</sub>	26N90	104	A
		25N90	100	
<b>I<sub>AR</sub></b>	T <sub>C</sub> = 25°C	26N90	26	A
		25N90	25	
<b>E<sub>AR</sub></b>	T <sub>C</sub> = 25°C	64	mJ	
<b>E<sub>AS</sub></b>	T <sub>C</sub> = 25°C	3	J	
<b>dv/dt</b>	I <sub>S</sub> ≤ I <sub>DM</sub> , di/dt ≤ 100 A/μs, V <sub>DD</sub> ≤ V <sub>DSS</sub> , T <sub>J</sub> ≤ 150°C, R <sub>G</sub> = 2 Ω	5	V/ns	
<b>P<sub>D</sub></b>	T <sub>C</sub> = 25°C	600	W	
<b>T<sub>J</sub></b>		-55 ... +150	°C	
<b>T<sub>JM</sub></b>		150	°C	
<b>T<sub>stg</sub></b>		-55 ... +150	°C	
<b>T<sub>J</sub></b>	1.6 mm (0.63 in) from case for 10 s	-	°C	
<b>V<sub>ISOL</sub></b>	50/60 Hz, RMS      t = 1 min	2500	V~	
	I <sub>ISOL</sub> ≤ 1 mA      t = 1 s	3000	V~	
<b>M<sub>d</sub></b>	Mounting torque	1.5/13	Nm/lb.in.	
	Terminal connection torque	1.5/13	Nm/lb.in.	
<b>Weight</b>		30	g	

<b>Symbol</b>	<b>Test Conditions</b>	<b>Characteristic Values</b>		
		(T <sub>J</sub> = 25°C, unless otherwise specified)		
		<b>min.</b>	<b>typ.</b>	<b>max.</b>
<b>V<sub>DSS</sub></b>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 3 mA	900		V
<b>V<sub>GH(th)</sub></b>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 8 mA	3.0	5.0	V
<b>I<sub>GSS</sub></b>	V <sub>GS</sub> = ±20 V <sub>DC</sub> , V <sub>DS</sub> = 0		±200	nA
<b>I<sub>DSS</sub></b>	V <sub>DS</sub> = 0.8 • V <sub>DSS</sub> T <sub>J</sub> = 25°C V <sub>GS</sub> = 0 V      T <sub>J</sub> = 125°C		100	μA
			2	mA
<b>R<sub>DS(on)</sub></b>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 • I <sub>D25</sub> Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %	26N90 25N90	0.30 0.33	Ω

IXYS reserves the right to change limits, test conditions, and dimensions.

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**Advantages**

- Easy to mount
- Space savings
- High power density

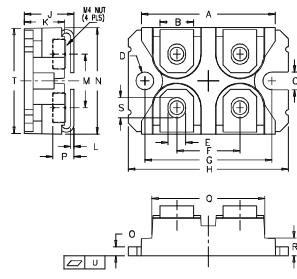
**Applications**

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- Temperature and lighting controls

**Features**

- International standard package
- miniBLOC, with Aluminium nitride isolation
- Low R<sub>DS(on)</sub> HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- Fast intrinsic Rectifier

Symbol	Test Conditions	Characteristic Values			
		( $T_j = 25^\circ\text{C}$ , unless otherwise specified)	min.	typ.	max.
$g_{fs}$	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$ , pulse test	18	28	S	
$C_{iss}$ $C_{oss}$ $C_{rss}$	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	8.7	10.8	nF	
		800	1000	pF	
		300	375	pF	
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1 \Omega$ (External)	60		ns	
		35		ns	
		130		ns	
		24		ns	
$Q_{g(on)}$ $Q_{gs}$ $Q_{gd}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$	240		nC	
		56		nC	
		107		nC	
$R_{thJC}$			0.21	K/W	
$R_{thCK}$			0.05	K/W	

**miniBLOC, SOT-227 B**


M4 screws (4x) supplied

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	38.00	38.23	1.496	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.76	0.84	0.030	0.033
M	12.60	12.85	0.496	0.506
N	25.15	25.42	0.990	1.001
O	1.98	2.13	0.078	0.084
P	4.95	5.97	0.195	0.235
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.174
S	4.72	4.85	0.186	0.191
T	24.59	25.07	0.968	0.987
U	-0.05	0.1	-0.002	0.004

**Source-Drain Diode**

Symbol	Test Conditions	Characteristic Values			
		( $T_j = 25^\circ\text{C}$ , unless otherwise specified)	min.	typ.	max.
$I_s$	$V_{GS} = 0 \text{ V}$	26N90 25N90		26 25	A
$I_{SM}$	Repetitive; pulse width limited by $T_{JM}$	26N90 25N90		104 100	A
$V_{SD}$	$I_F = I_S, V_{GS} = 0 \text{ V},$ Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2 \%$			1.5	V
$t_{rr}$ $Q_{RM}$ $I_{RM}$	$I_F = I_S, -di/dt = 100 \text{ A}/\mu\text{s}, V_R = 100 \text{ V}$		1.4 10	250	ns $\mu\text{C}$ A

Figure 1. Output Characteristics at 25°C

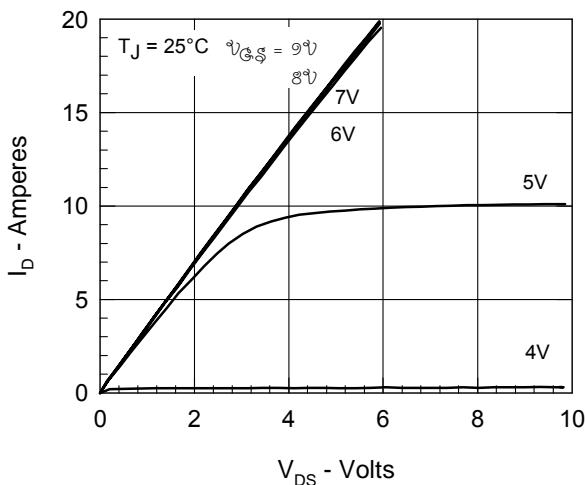


Figure 3.  $R_{DS(on)}$  normalized to 0.5  $I_{D25}$  value vs.  $I_D$

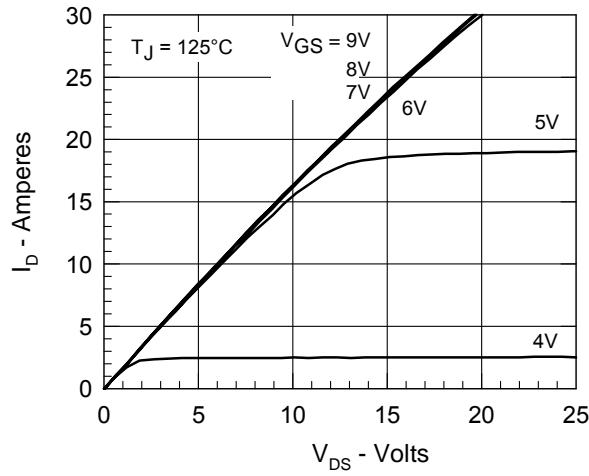


Figure 5.  $R_{DS(on)}$  normalized to 0.5  $I_{D25}$  value vs.  $I_D$

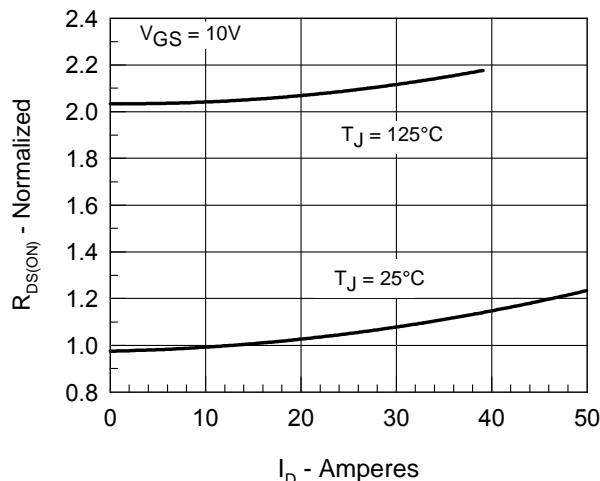


Figure 2. Extended Output Characteristics at 125°C

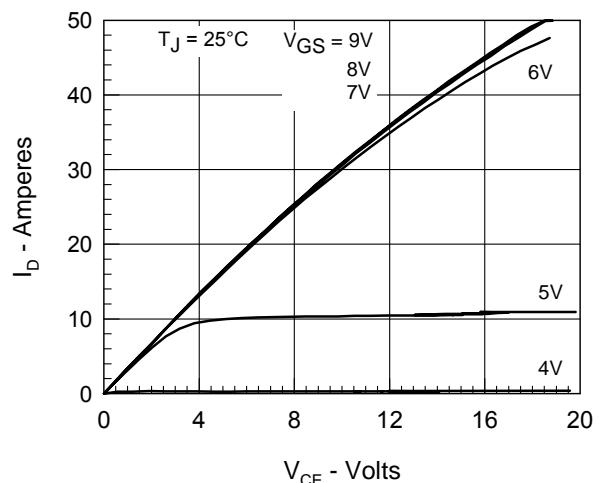


Figure 4. Admittance Curves

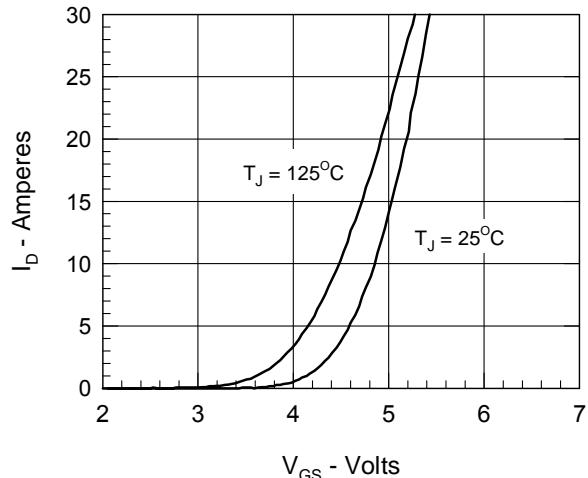


Figure 6.  $R_{DS(on)}$  normalized to 0.5  $I_{D25}$  value vs.  $T_J$

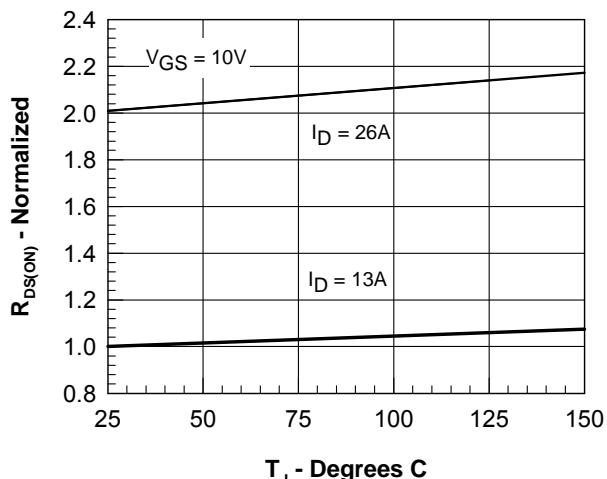


Figure 7. Gate Charge

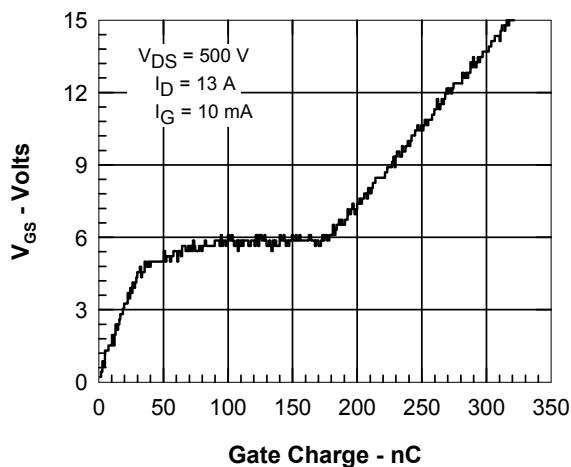
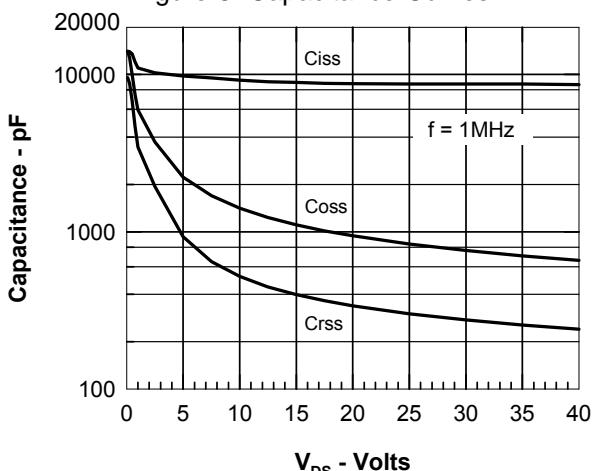


Figure 8. Capacitance Curves



Capacitance Curves

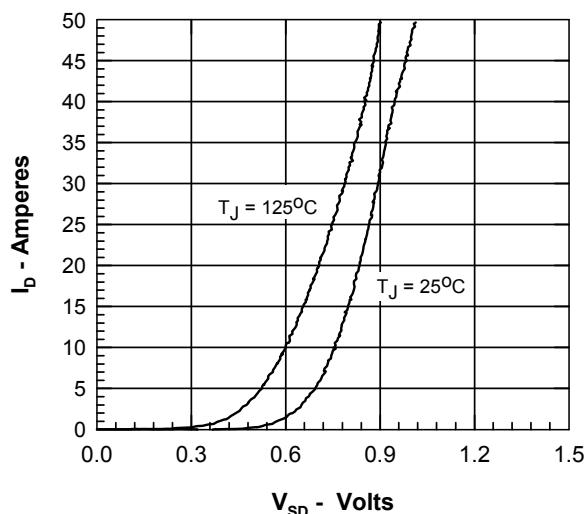


Figure 10. Drain Current vs. Case Temperature

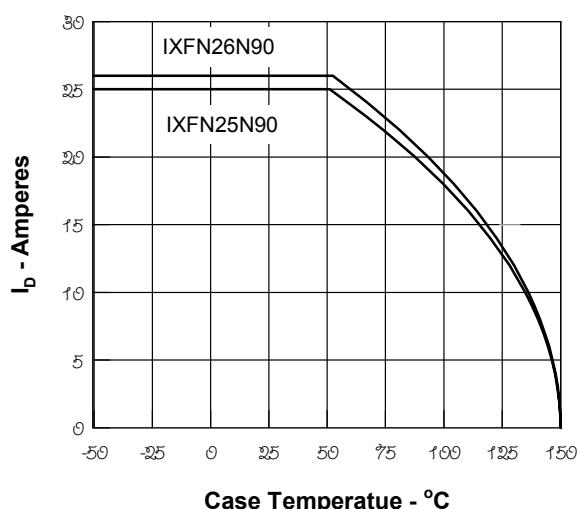
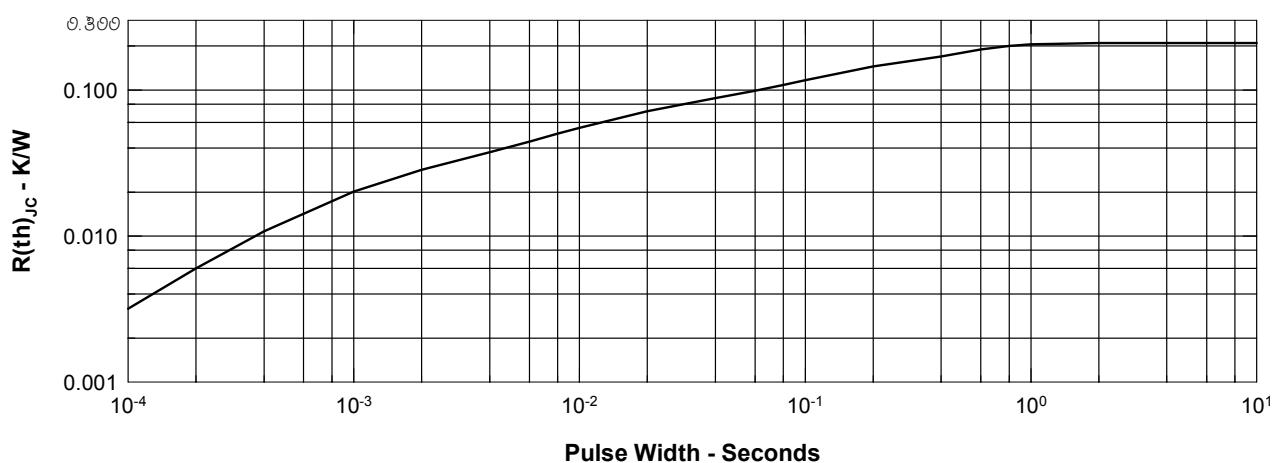


Figure 11. Transient Thermal Resistance



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